

JC962 U.S. PTO
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E. Willis
8-20-02

NON-PROVISIONAL APPLICATION FOR U. S. PATENT UNDER 37 CFR 1.53(b)
TRANSMITTAL FORM

Attorney Docket No. TI-31373

Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the
patent application of:

Inventor(s): **Gary P. Morrison**
Darvin R. Edwards
Leslie Stark

For: **CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR FOR VERTICAL
ASSEMBLY ON SUBSTRATES**

Enclosed are:

- 5 Sheets of formal drawings and 28 pages of Specification (including Abstract)
x A Declaration/Power of Attorney
 Assignment with form PTO 1595

Please amend the specification by inserting before the first line the sentence:

This application claims priority under 35 U.S.C. § 119 based upon **Provisional Patent
Application number 60/258,525 filed 12/28/2000.**

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 740.00
Total Claims	23	-20 =	3	X \$18 =	\$54.00
Independent Claims	6	- 3 =	3	X \$84 =	\$252.00
Total Filing Fee					\$1046.00

Please charge **Deposit Account No. 20-0668** in the amount of the Total Fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 20-0668. **This form is submitted in triplicate.**

All correspondence related to this application may be addressed to the undersigned at Godwin Grubber, P.C. 801 E. Campbell Rd. Suite 655, Richardson, TX 75081.

Date: December 26, 2001

Gary C. Honeycutt
Gary C. Honeycutt
Registration No. 20,250

"EXPRESS MAILING" Mailing Label No. EV051432549US.
Date of Deposit: December 26, 2001. I hereby certify that this
paper is being deposited with the U.S. Postal Service Express Mail
Post Office to Addressee Service under 37 CFR 1.10 on the
date shown above and is addressed to the Assistant Commissioner
for Patents, Washington, D.C. 20231.
Emilio C. Chantry Date 12/26/01

JC825 U.S. PTO

10/034827

01/03/02

G O D W I N G R U B E R

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December 26, 2001

EV051432549US

VIA EXPRESS MAIL

Assistant Commissioner for Patents
Washington, D.C. 20231

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Re: Patent Application For
**CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR
FOR VERTICAL ASSEMBLY ON SUBSTRATES**
Attorney Docket No. TI-31373
Our File: 50000.2166

Dear Sir:

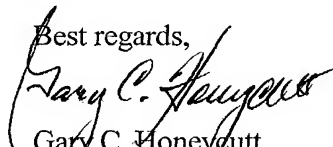
Enclosed for filing please find the following items relating to the above-identified application:

- (1) Non-Provisional Application/Fee Authorization/transmittal Form ;
- (2) Declaration, and Power of Attorney;
- (3) Recordation Form Cover Sheet with Assignment;
- (4) Specifications and Formal Drawings; and
- (5) Postcards.

Please charge **Deposit Account No. 20-0668** in the amount of the total fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to **Deposit Account No. 20-0668**.

Please file the application and return the date-stamped postcard to the corresponding addresses as indicated. In the meantime, if you have any questions or comments concerning this matter, please call the undersigned. Otherwise, please accept the enclosed.

Best regards,


Gary C. Honeycutt
Reg. No. 20,250

GCH/ecc

Encls.

cc: Larry Bassuk, Texas Instruments Incorporated

PATENT APPLICATION SERIAL NO. _____

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE
FEE RECORD SHEET

01/07/2002 TGEDANU1 00000056 200668 10034627

01 FC:101	740.00 CH
02 FC:102	252.00 CH
03 FC:103	54.00 CH

PTO-1556
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*U.S. GPO: 2000-468-987/39595